

**IN THE UNITED STATES DISTRICT COURT
FOR THE EASTERN DISTRICT OF TEXAS
MARSHALL DIVISION**

TESSERA ADVANCED TECHNOLOGIES,
INC.,

Plaintiff,

v.

SAMSUNG ELECTRONICS CO., LTD. and
SAMSUNG ELECTRONICS AMERICA,
INC.,

Defendants.

Case No. 2:17-cv-00671-JRG

JURY TRIAL DEMANDED

P.R. 4-5 JOINT NOTICE REGARDING CLAIM CONSTRUCTION CHART

Pursuant to Patent Rule 4-5(d) and the Court’s Docket Control Order (Dkt. 46), Plaintiff Tessera Advanced Technologies, Inc. (“Tessera”) and Defendants Samsung Electronics Co., Ltd. and Samsung Electronics America, Inc. (collectively, “Samsung”) hereby file this Joint Claim Construction Chart. The parties have not agreed to any constructions at this time. Attached as Appendix A are the claims with the disputed language in bold type, along with the parties’ respective proposed constructions, and a column for the Court’s construction. Appendix A includes a separate table for each of the patents-in-suit. A simplified version grouping similar terms is attached as Appendix B, which may be more helpful for the Court’s purposes.

The following terms are in dispute:

- ’298/’616 Patents
 - “external electrode” / “external electrode terminal” – ’298 patent claims 1, 8, 10; ’616 patent claims 1, 8, 9
 - “forming a second, thick conductive film selectively on the first, thin conductive film so as to fill up the first opening and the second opening” – ’616 patent claim 1

- “a protective film formed ... having a property of repelling conductive material” / “forming a protective film having a property of repelling conductive material” – ’298 patent claim 8; ’616 patent claim 8

Dated: August 31, 2018

Respectfully submitted,

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CERTIFICATE OF SERVICE

I hereby certify that a copy of the foregoing document was filed electronically in compliance with Local Rule CV-5(a). Therefore, this document was served on all counsel who are deemed to have consented to electronic service. Local Rule CV-5(a)(3)(A). Pursuant to Fed. R. Civ. P. 5(d) and Local Rule CV-5(d) and (e), all other counsel of record not deemed to have consented to electronic service were served with a true and correct copy of the foregoing by email on this 31st day of August, 2018.

/s/ Linda Smith
Linda Smith

APPENDIX A

APPENDIX A

APPENDIX A

I. U.S. PATENT NOS. 6,512,298 (CLAIMS 1-4 AND 8-10)

'298 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
Claim 1				
1. A semiconductor device comprising:				
a semiconductor substrate provided with at least one semiconductor element;				
a first element electrode and a second element electrode formed on the semiconductor substrate and connected electrically to the semiconductor element;				
an insulating film formed so as to cover the first element electrode and the second element electrode;				
a first opening formed on the insulating film and exposing at least one portion of the first element electrode;				
a second opening formed on the insulating film and exposing at least one portion of the second element electrode;				

APPENDIX A

'998 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
a first external electrode formed immediately above the first element electrode and connected to the first element electrode via the first opening;	"external electrode"	"electrode for connecting a package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
a second external electrode formed on the insulating film; and	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
a connecting wire formed on the insulating film and having one end connected to the second element electrode via the second opening and the other end connected to the second external electrode .	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
Claim 2				
2. The semiconductor device of claim 1, wherein the semiconductor substrate is a semiconductor wafer.				
Claim 3				

APPENDIX A

'298 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
3. The semiconductor device of claim 1, wherein the semiconductor substrate is a chip obtained by dividing a semiconductor wafer.				
Claim 4				
4. The semiconductor device of claim 1, wherein the insulating film is made of elastic insulating material.				
Claim 8				
8. The semiconductor device of claim 1 further comprising:				
a protective film formed so as to cover the first external electrode , the second external electrode and the connecting wire and having a property of repelling conductive material ;	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
	"a protective film formed ... having a property of repelling conductive material"	Plain and ordinary meaning, no construction necessary	Indefinite	

APPENDIX A

'298 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
a fourth opening formed on the protective film and exposing at least one portion of the first external electrode ;	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
a fifth opening formed on the protective film and exposing at least one portion of the second external electrode ;	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
a first external electrode terminal formed immediately above the first external electrode and connected to the first external electrode via the fourth opening; and	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
	"external electrode terminal"	"terminal on the outer surface of the package for connection to external equipment"	"metallic ball, conductive bump, or a portion of the [first/second] external electrode, configured to	

APPENDIX A

'998 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
			connect to external equipment"	
a second external electrode terminal formed immediately above the second external electrode and connected to the second external electrode via the fifth opening.	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
	"external electrode terminal"	"terminal on the outer surface of the package for connection to external equipment"	"metallic ball, conductive bump, or a portion of the [first/second] external electrode, configured to connect to external equipment"	
Claim 9				
9. The semiconductor device of claim 1, further comprising a passivation film covering the surface of the semiconductor substrate except the first element electrode and the second element electrode,				
wherein the insulating film is formed above the passivation film.				

APPENDIX A

'998 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
Claim 10				
10. The semiconductor device of claim 8, wherein the first external electrode terminal and the second external electrode terminal are formed of metallic balls.	"external electrode terminal"	"terminal on the outer surface of the package for connection to external equipment"	"metallic ball, conductive bump, or a portion of the [first/second] external electrode, configured to connect to external equipment"	

APPENDIX A

II. U.S. PATENT NO. 6,852,616 (CLAIMS 1-6, 8, AND 9)

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
Claim 1				
1. A method for producing a semiconductor device comprising:				
a first step of forming on a semiconductor substrate on which at least one semiconductor element is provided a first element electrode and a second element electrode electrically connected to the semiconductor element;				
a second step of forming an insulating film so as to cover the first element electrode and the second element electrode;				
a third step of forming a first opening for exposing at least one portion of the first element electrode and a second opening for exposing at least one portion of the second element electrode by				

APPENDIX A

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
selectively removing the insulating film;				
a fourth step of forming first substantially continuous, thin conductive film on the insulating film and within the first and second openings;				
A fifth step of forming a second, thick conductive film selectively on the first, thin conductive film so as to fill up the first opening and the second opening and extend over portions of the first, thin conductive film between the first and second openings; and	"forming a second, thick conductive film selectively on the first, thin conductive film so as to fill up the first opening and second opening"	Plain and ordinary meaning, which includes: "forming a second, thick conductive film selectively on the first, thin conductive film so as to plug or span the first opening and second opening."	Indefinite as to "a second, thick conductive film selectively on the first, thin conductive film" Plain and ordinary meaning for the remainder of the term	
a sixth step of patterning the first and second conductive films by removing only an upper portion of the selectively formed second, thick conductive film and portions of the first, thin conductive film uncovered	"external electrode"	"electrode for connecting a package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	

APPENDIX A

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
by the second, thick conductive film, thereby forming a first external electrode connected to the first element electrode via the first opening immediately above the first element electrode, forming a second external electrode and forming a connecting wire having one end connected to the second element electrode via the second opening and the another end connected to the second external electrode on the insulating film.				
Claim 2				
2. The method for producing a semiconductor device of claim 1, wherein the semiconductor substrate is a semiconductor wafer; and				
the method further composes a step of dividing the semiconductor				

APPENDIX A

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
wafer into chips after the fourth step.				
Claim 3				
3. The method for producing a semiconductor device of claim 1, wherein the semiconductor substrate is obtained by dividing a semiconductor wafer into chips.				
Claim 4				
4. The method for producing a semiconductor device of claim 1, wherein the insulating film is made of elastic insulating material.				
Claim 5				
5. The method for producing a semiconductor device of claim 1, wherein the third step comprises a step of forming the first opening and the second opening so that each wall surface of the openings has an inclination of less than 90° with respect to a				

APPENDIX A

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
surface of the semiconductor substrate.				
Claim 6				
6. The method for producing a semiconductor device of claim 1, wherein the third step comprises a step of forming the first opening and the second opening so that at least portions near the upper end and near the lower end of each wall surface of the openings have an inclination of less than 90° with respect to a surface of the semiconductor substrate.				
Claim 8				
8. The method for producing a semiconductor device of claim 1, further comprising a seventh step of forming a protective film having a property of repelling conductive material so as to cover the first external electrode , the second external	"external electrode"	"electrode for connecting the package to external equipment"	"portion of a conductive pattern configured to contact an 'external electrode terminal' (as defined below) or external equipment"	
	"forming a protective film	Plain and ordinary meaning, no	Indefinite	

APPENDIX A

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
electrode and the connecting wire and then selectively removing the protective film to form a fourth opening for exposing at least one portion of the first external electrode and a fifth opening for exposing at least one portion of the second external electrode , after the sixth step.	having a property of repelling conductive material”	construction necessary.		
Claim 9				
9. The method for producing a semiconductor device of claim 8, wherein the seventh step comprises a step of forming a first external electrode terminal connected to the first external electrode via the fourth opening immediately above the first external electrode and forming a second external electrode terminal connected to the second external electrode via the fifth opening immediately	“external electrode”	“electrode for connecting the package to external equipment”	“portion of a conductive pattern configured to contact an ‘external electrode terminal’ (as defined below) or external equipment”	
	“external electrode terminal”	“terminal on the outer surface of the package for connection to external equipment”	“metallic ball, conductive bump, or a portion of the [first/second] external electrode, configured to connect to external equipment”	

APPENDIX A

'616 Patent Claim Language	Disputed Terms	Plaintiff's Proposed Construction	Defendants' Proposed Construction	Court's Construction
above the second external electrode .				

APPENDIX B

APPENDIX B

APPENDIX B**I. U.S. PATENT NOS. 6,512,298 (CLAIMS 1-4 AND 8-10) AND 6,852,616 (CLAIMS 1-6, 8, AND 9)**

Claim Terms From '298/'616 Patents	Plaintiff's Proposed Constructions	Defendants' Proposed Constructions	Court's Construction
<p>“external electrode”</p> <p>'298 patent claims 1, 8, 12-13</p> <p>'616 patent claims 1, 8, 9</p>	<p>“electrode for connecting a package to external equipment”</p>	<p>“portion of a conductive pattern configured to contact an ‘external electrode terminal’ (as defined below) or external equipment”</p>	
<p>“external electrode terminal”</p> <p>'298 patent claims 8, 10-13</p> <p>'616 patent claim 9</p>	<p>“terminal on the outer surface of the package for connection to external equipment”</p>	<p>“metallic ball, conductive bump, or a portion of the [first/second] external electrode, configured to connect to external equipment”</p>	
<p>“forming a second, thick conductive film selectively on the first, thin conductive film so as to fill up the first opening and the second opening”</p> <p>'616 patent claim 1</p>	<p>Plain and ordinary meaning, which includes:</p> <p>“forming a second, thick conductive film selectively on the first, thin conductive film so as to plug or span the first opening and second opening.”</p>	<p>Indefinite as to “a second, thick conductive film selectively on the first, thin conductive film”</p> <p>Plain and ordinary meaning for the remainder of the term</p>	
<p>“a protective film formed ... having a property of repelling</p>	<p>Plain and ordinary meaning, no construction necessary</p>	<p>Indefinite</p>	

APPENDIX B

Claim Terms From '298/'616 Patents	Plaintiff's Proposed Constructions	Defendants' Proposed Constructions	Court's Construction
conductive material” / “forming a protective film having a property of repelling conductive material” '298 patent claim 8 '616 patent claim 8			

